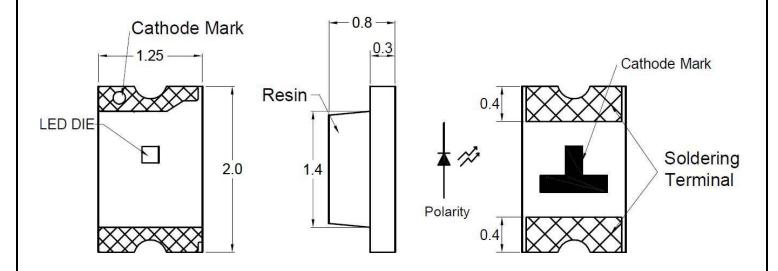
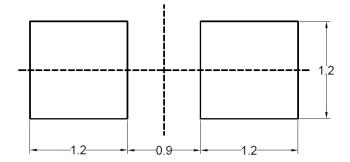


2.0 x 1.25 x 0.8 mm Pure Green SMD LED

PACKAGE DIMENSION



Recommended Solder Pad



NOTES:

- 1. All dimensions are in millimeters (inches);
- 2. Tolerances are ± 0.1 mm unless otherwise noted.

Chip Material	Chip Emitted	Lens Color	Viewing Angle
InGaN/GaN	Pure Green	Water Clear	130



2.0 x 1.25 x 0.8 mm Pure Green SMD LED

ABSOLUTE MAXIMUM RATINGS

(Ta=25°C)

Parameter	Symbol	Value	Unit
Forward current	If	20	mA
Reverse current @ 5V	Ir	10	μΑ
Power dissipation	Pd	80	mW
Operating temperature range	Тор	-20~+80	°C
Storage temperature range	Tstg	-30~+100	°C
Electrostatic Discharge	ESD	2000	V
Peak pulsing current (1/10 duty f= 10KHz)	lfp	100	mA

OPTICAL-ELECTRICAL CHARACTERISTICS

(Ta=25°C)

Danasalas	Symbol Test Condition	Value		1.1.20		
Parameter		Test Condition	Min	Тур	Max	Unit
Wavelength at peak emission	λpeak	I _F = 20mA	-	518	-	nm
Spectral half bandwidth	Δλ	I _F = 20mA	-	36	ı	nm
Dominant wavelength	λdom	I _F = 20mA	-	525	1	Nm
Forward Voltage	Vf	I _F = 20mA	2.8	1	3.6	V
Luminous intensity	lv	I _F = 20mA	125	250	ı	mcd
Viewing angle at 50% lv	20 ½	I _F = 20mA		130	-	Deg

^{*}Note: 1. The forward voltage data did not include ±0.1V testing tolerance.

^{2.} The luminous intensity data did not include ±15% testing tolerance.

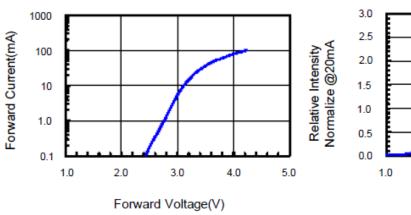


2.0 x 1.25 x 0.8 mm Pure Green SMD LED

OPTICAL CHARACTERISTIC CURVES

Fig.1 Forward current vs. Forward Voltage

Fig.2 Relative Intensity vs. Forward Current



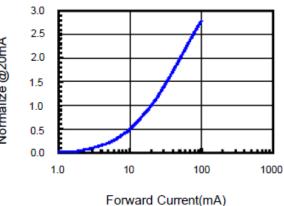
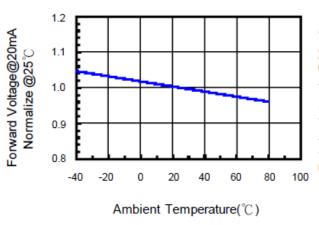


Fig.3 Forward Voltage vs. Temperature

Fig.4 Relative Intensity vs. Temperature



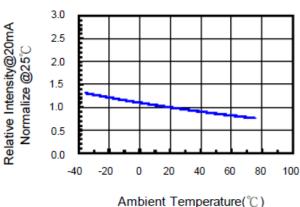
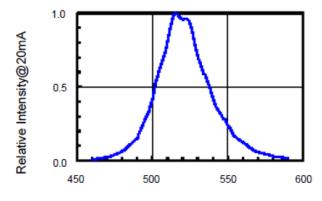
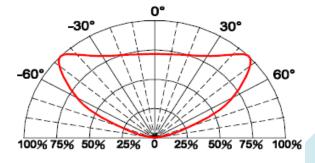


Fig.5 Relative Intensity vs. Wavelength

Fig.6 Directive Radiation







2.0 x 1.25 x 0.8 mm Pure Green SMD LED

LUMINOUS INTENSITY BIN TABLE

Croup	Iv(mcd) @ 20mA		Lloit
Group	Min	Max	Unit
R	125	200	
S	200	320	nm
Т	320	500	nm
U	500	800	

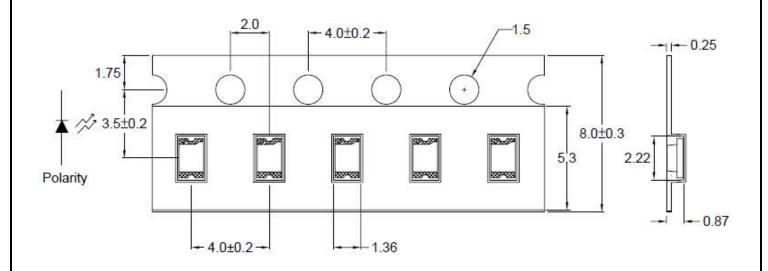
DOMINANT WAVELENGTH BIN TABLE

Group	(mcd) @ 20mA		Unit
Group	Min	Max	Offic
10	519	522	
1P	522	525	nm
1Q	525	528	nm
1R	528	531	



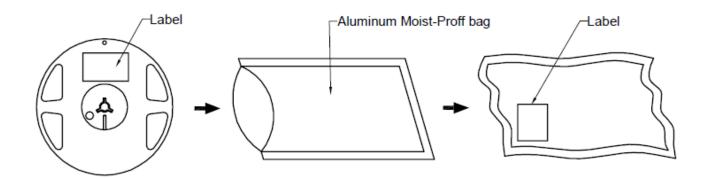
2.0 x 1.25 x 0.8 mm Pure Green SMD LED

Dimensions of Tape (Unit: mm)



Note: The tolerances unless mentioned are ±0.1mm, Angle ±0.5; Unit=mm

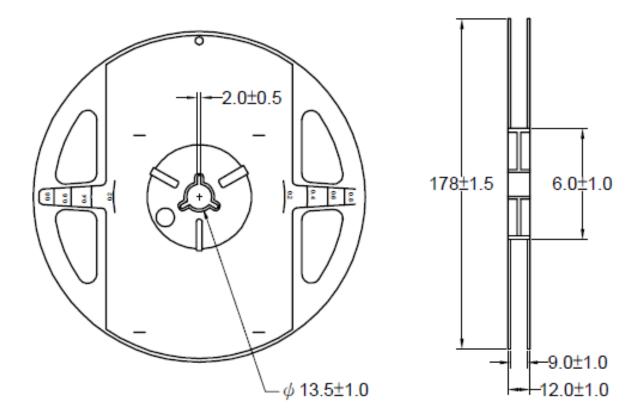
PACKAGING SPECIFICATION





2.0 x 1.25 x 0.8 mm Pure Green SMD LED

REEL DIMENSIONS



Notes:

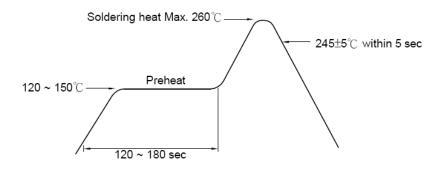
- 1. Empty component pockets are sealed with top cover tape;
- 2. The maximum number of missing lamps is two;
- 3. The cathode is oriented towards the tape sprocket hole.
- 4. 4,000pcs/Reel



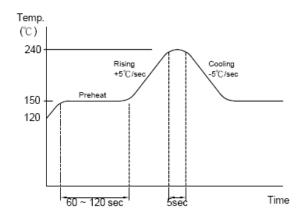
2.0 x 1.25 x 0.8 mm Pure Green SMD LED

Recommended Soldering Conditions

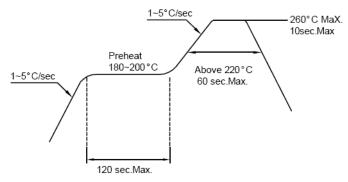
- Hand Solder
 Basic spec is ≤ 280°C 3 sec one time only.
- 2. Wave Solder



3-1. LEAD Reflow Solder



3-2. PB-Free Reflow Solder



Note: Reflow soldering should not be done more than two times.



2.0 x 1.25 x 0.8 mm Pure Green SMD LED

PRECAUTIONS FOR USE

Storage Time:

- 1. The operation of temperatures and RH are: 5°C~35°C, RH60%.
- 2. Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp proof box with descanting agent. Considering the tape life, we suggest our customers to use our products within a year (from production date).
- 3. If opened more than one week in an atmosphere 5°C~35°C, RH60%, they should be treated at 60°C±5°C for 15hrs.

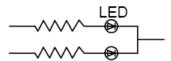
Drive Method:

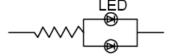
LED is a current operated device, and therefore, require some kind of current limiting incorporated into the driver circuit. This current limiting typically takes the form of a current limiting resistor placed in a series with the LED.

Consider worst case voltage variations that could occur across the current limiting resistor. The forward current should not be allowed to change by more than 40% of its desired value.

Circuit model A

Circuit model B





- (A) Recommended circuit.
- (B) The difference of brightness between LED could be found due to the VF-IF characteristics of LED.

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED.

ESD(Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or antielectrostatic glove is recommended when handling these LEDs. All devices and machinery must be properly grounded.



2.0 x 1.25 x 0.8 mm Pure Green SMD LED

RELIABILITY TEST

Classification	Test Item	Test Condition	Reference Standard
Endurance Test	Operating Life Test	1.Ta=Under Room Temperature As Per Data Sheet Maximum Rating. 2.If=20mA 3.t=1000 hrs (-24hrs, +72hrs)	MIL-STD-750D: 1026 MIL-STD-883D: 1005 JIS C 7021: B-1
	High Temperature Storage Test	1.Ta=105°C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	MIL-STD-883D:1008 JIS C 7021: B-10
	Low Temperature Storage Test	1.Ta=-40°C±5°C 2.t=1000 hrs (-24hrs, +72hrs)	JIS C 7021: B-12
	High Temperature High Humidity Storage Test	1.Ta=65°C±5°C 2.RH=90%~95% 3.t=1000hrs±2hrs	MIL-STD-202F:103B JIS C 7021: B-11
Environmental Test	Thermal Shock Test	1.Ta=105°C±5°C &-40°C±5°C (10min) (10min) 2.total 10 cycles	MIL-STD-202F: 107D MIL-STD-750D: 1051 MIL-STD-883D: 1011
	Solderability Test	1.T.Sol=235°C±5°C 2.Immersion time 2±0.5sec 3.Coverage ≥95% of the dipped surface	MIL-STD-202F: 208D MIL-STD-750D: 2026 MIL-STD-883D: 2003 IEC 68 Part 2-20 JIS C 7021: A-2
	Temperature Cycling	1.105°C ~ 25°C ~ -55°C ~ 25°C 30mins 5mins 30mins 5mins 2.10 Cyeles	MIL-STD-202F: 107D MIL-STD-750D: 1051 MIL-STD-883D: 1010 JIS C 7021: A-4
	IR Reflow	1.T=260°C Max. 10sec.Max. 2. 6 Min	MIL-STD-750D:2031.2 J-STD-020